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(71) Applicant : FUJI ELECTRIC CO LTD

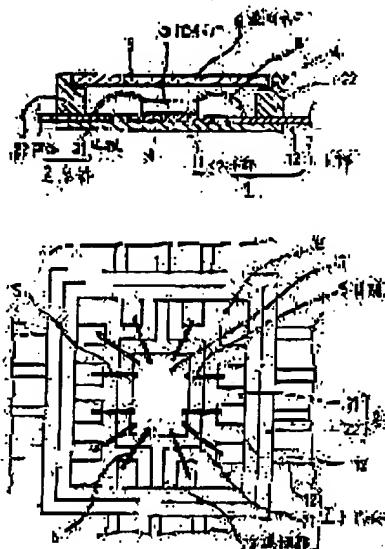
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(72) Inventor : SHIRAHATA HISASHI

(54) MANUFACTURE OF SEMICONDUCTOR DEVICE**(57) Abstract:**

PURPOSE: To improve mass productivity by completing each process of burying a lead frame into a resin vessel, the fixing of a chip including a photodetector, the connection of the chip and a lead and the fastening of a transparent window in the state in which a lead frame is connected, and cutting the lead frame.

CONSTITUTION: At least both end sections of lead sections 12 and at least one surface of a mount section 11 are exposed in a multiple type lead frame 1, and buried into a resin body consisting of a frame body 22 and a bottom plate 21, and a chip 3 is fixed to the mount section 11 for the lead frame 1. Terminals for the chip 3 and one end sections of the lead sections 12 are connected by conductors, the peripheral section of a transparent cover body is fastened to the frame body, and the lead frame is cut and divided. Accordingly, assembly can be executed collectively, thus improving mass productivity.

**LEGAL STATUS**

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